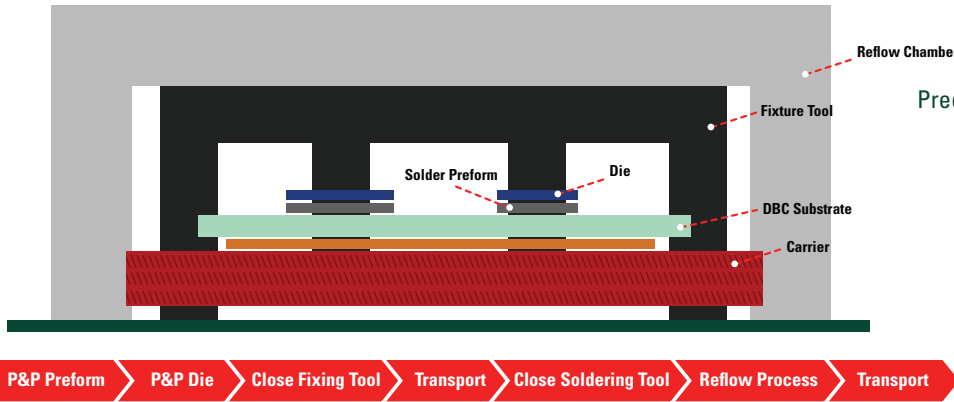


# SOLUTIONS FOR POWER MODULE ASSEMBLY

## THE CHALLENGE:

### Power Module Assembly Tooling



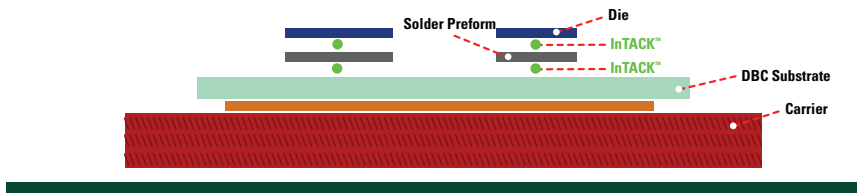
Precise assembly alignment is required to ensure long-term reliability and consistent quality



Elaborate fixture tools are expensive to design/maintain, and add complexity to the reflow process

## THE SOLUTION:

### InTACK™ Technology



Tacking material maintains alignment during assembly and reflow

✓ No Tooling/  
Fixturing Required

✓ Simplified  
Reflow Process

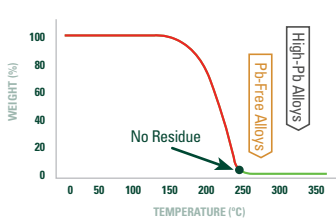
✓ Reduced  
Reflow Time

✓ Reduced Overall  
Process Time

Dispense InTACK™ -> P&P Preform -> P&P Die -> Transport -> Reflow Process -> Transport

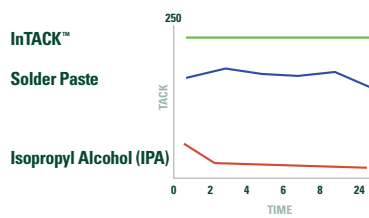
#### No Residue After Reflow

Ideal for no-flux soldering and sintering applications



Residue Analysis

#### Consistent High-Tack Strength Over Time



High-Tack and Long Working Time

#### Benefits:

- ✓ Maintain precise solder preform and assembly alignment
- ✓ Robust tacking and long working time
- ✓ Optimal performance in formic acid/vacuum reflow
- ✓ No impact to solder wetting, voiding
- ✓ No cleaning needed, no post-processing
- ✓ Dispensing application tested and process proven

InTACK™ Technology is specifically designed to achieve high-quality solder performance, with no residue in flux-free reflow techniques commonly used in power module assembly.

Learn more: [www.indium.com](http://www.indium.com)

**From One Engineer To Another®**

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

